



PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT I - PCN # : A1608-02

PCN Type: Manufacturing Site - Alternate Assembly Location

Data Sheet Change: None

No change in moisture sensitivity level (MSL)

Detail Of Change:

This notification is to advise our customers that IDT is adding SFA Semicon Co. Ltd, Korea (previously named as STS Semiconductor & Telecommunication Co. Ltd) as an alternate assembly facility for parts that are currently assembled at ASEK and ASECL, Taiwan.

The material set details of the current and alternate assembly location is as shown in Table 1.

There is no change to the moisture performance.

Table 1: Assembly Material Sets for The Existing and Alternate Assembly Location

	Existing Assembly (ASE Kaohsiung, Taiwan & ASE Chungli, Taiwan)	Alternate Assembly (SFA, Korea)
Die Bump	Sn1.8Ag	Sn1.8Ag
Mold Compound	KE-G1250FC-20B	Panasonic CV8710U
Substrate	ABF-GX13/E700GR core	ABF-GX13/E700GR core
Solder Balls	Sn98.25/Ag1.2/Cu0.50/Ni0.05	Sn98.25/Ag1.2/Cu0.50/Ni0.05



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Qualification Information and Qualification Data:

Affected Packages: FCCSP-53

Assembly Material: Shown on page 2 of this attachment.

Qual Plan & Results: Tests are in accordance with JEDEC47 recommended tests.

Qualification Vehicle: FCCSP-53

Test Description	Test Method	Test Results (Rej / SS)		
		Lot 1	Lot 2	Lot 3
* Temperature Cycling (-55°C to 125°C, 700 cycles)	JESD22-A104	0/25	0/25	0/25
* HAST - biased (130 °C/85% RH, 96 Hrs)	JESD22-A110	0/25	0/25	0/25
High Temperature Storage Bake (150°C, 1000 Hrs)	JESD22-A103	0/25	0/25	0/25
Solder Ball Shear Test	JESD22-B117	0/5	0/5	0/5
Moisture Sensitivity Level, MSL	J-STD-20 / MSL 3, 260 °C	0/25	0/25	0/25

* Tests were subjected to Preconditioning per JESD22-A113 prior to stress test